

**AMENDMENTS TO THE CLAIMS**

Please replace the claims, including all prior versions, with the listing of claims below.

**Listing of Claims:**

1. (Currently amended) A method for manufacturing pins, comprising:  
punching out at least one pin from a basic body by at least one punching process step;  
[[and]]  
coating the pin or a section of the pin with a separate metal layer after completion of the punching out of the pin, wherein at least one metal deposition process step is used for coating the pin with the separate metal layer; and  
generating, for carrying out the deposition process step, a galvanizing potential at the pin by a corresponding voltage being applied at at least one of a further pin of the semiconductor device and side web of the semiconductor device electrically connected with the pin internally via the semiconductor device.
2. (Original) The method according to claim 1, wherein the front face at an outer end section of the pin is coated with the metal layer.
3. (Canceled)
4. (Original) The method according to claim 1, further comprising mounting the basic body in a housing.
5. (Original) The method according to claim 4, wherein the mounting of the basic body in the housing takes place prior to completion of the punching out of the pin.
6. (Original) The method according to claim 1, wherein a plurality of pins positioned side by side are punched out from the basic body.

7. (Original) The method according to claim 6, wherein the pins positioned side by side are coated with a separate metal layer after completion of the punching out of the pins.
8. (Original) The method according to claim 6, wherein at least one of the plurality of pins positioned side by side is coated with a separate metal layer after completion of the punching out of the corresponding pin, and wherein the coating with a separate metal layer is performed with the remaining pins prior to completion of the punching out of the respective pins.
9. (Original) The method according to claim 8, wherein the at least one pin is, with respect to the remaining pins, positioned side by side, and positioned further outside or outermost.
10. (Withdrawn) A semiconductor device pin configured to be manufactured by punching and/or metal coating processes from a basic body, wherein a finished condition of the pin, and a front face at an outer pin end section is coated with a separate metal layer.
11. (Withdrawn) A housing for semiconductor devices, comprising:  
a plurality of pins configured to be manufactured by punching and/or metal coating processes from a basic body, wherein at least one pin, in a finished condition, has a front face at an outer pin end section coated with a separate metal layer.
12. (Canceled)
13. (Canceled)
14. (Original) The method according to claim 1, wherein the basic body is a lead frame.
15. (Canceled)

16. (Original) The method according to claim 4, wherein the housing is a semiconductor device housing.
17. (New) The method according to claim 1, wherein the further pin of the semiconductor device is electrically connected with the pin via a diode.
18. (New) The method according to claim 2, wherein the diode is an ESD protection diode.